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## **BIB DATA SHEET**

## **CONFIRMATION NO. 6791**

10/517,765 02/03/2006 RULE  APPLICANTS Takashi Ozaki, Nakano-ku, JAPAN; Kenichi Suzaki, Nakono-ku, JAPAN; ** CONTINUING DATA **********************************	SERIAL NUM	MBER FILING OF				GROUP ART UNIT		ATTORNEY DOCKET			
APPLICANTS Takashi Ozaki, Nakano-ku, JAPAN; Kenichi Suzaki, Nakano-ku, JAPAN; ***CONTINUING DATA***** This application is a 371 of PCT/JP03/08097 06/26/2003 ***FOREIGN APPLICATIONS**** JAPAN 2002-187566 06/27/2002 JAPAN 2002-084774 03/26/2003 ***IF REQUIRED, FOREIGN FILING LICENSE GRANTED ** 09/14/2006  Foreign Priority claimed	10/517,76					438	2813	2813			
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Foreign Priority claimed	JAPAN 20	002-187	7566 06/27/20	002	******	<b>*</b>					
35 USC 119(a-d) conditions met 2 Yes \ No Verified and Sonya D McCall SHEPARD/ Examiner's Signature  Acknowledged											
Verified and Acknowledged  Ack	9 ,			Met after				_		INDEPENDENT CLAIMS	
ADDRESS  KRATZ, QUINTOS & HANSON, LLP 1420 K Street, N.W. Suite 400 WASHINGTON, DC 20005 UNITED STATES  TITLE  Substrate treating apparatus and method for manufacturing semiconductor device  FILING FEE RECEIVED 1630  FEES: Authority has been given in Paper No to charge/credit DEPOSIT ACCOUNT No for following:    All Fees     All Fees     1.16 Fees (Filing)     1.17 Fees (Processing Ext. of time)     1.18 Fees (Issue)     Other	Verified and	Verified and /SONYA D MCCALL SHEPARD/			arice	JAPAN	12	18		6	
1420 K Street, N.W. Suite 400 WASHINGTON, DC 20005 UNITED STATES  TITLE  Substrate treating apparatus and method for manufacturing semiconductor device  FILING FEE RECEIVED 1630  FEES: Authority has been given in Paper No to charge/credit DEPOSIT ACCOUNT No for following:    All Fees											
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